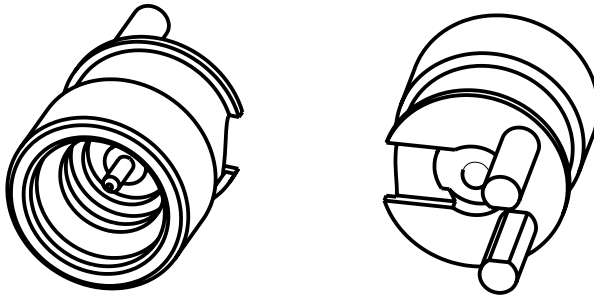
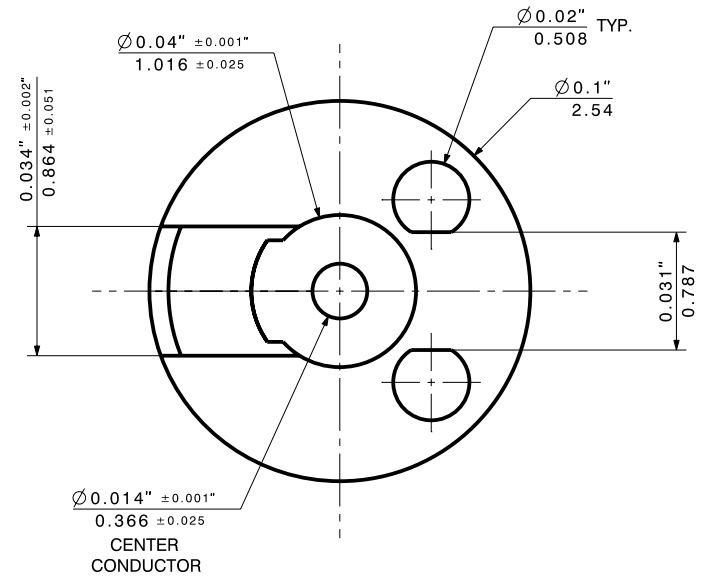
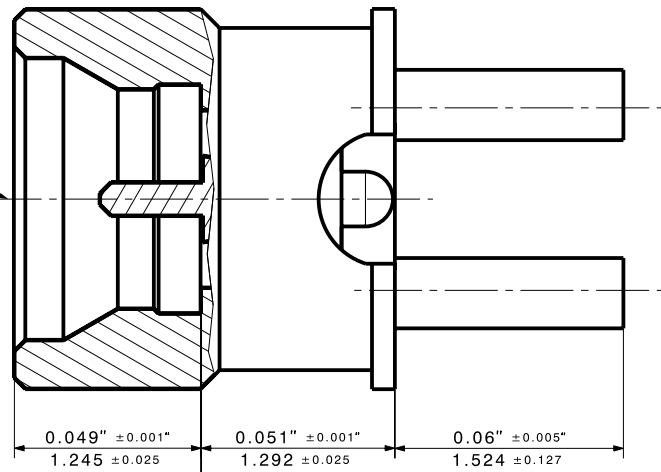


SMP3 Male  
Full Detent



Component	Material	Material Std compliance	Finish		Finish Std compliance
Body	Beryllium Copper	ASTM B-196 UNS No. C17300 Temper TD04(H)	Gold Plate Nickel underplate	50µIN - 100µIN [1.27µM - 2.54µM]	Gold per ASTM B-488, Code C, Type II, Class 1.27
				50µIN - 100µIN [1.27µM - 2.54µM]	Nickel per SAE-AMS-QQ-N-290, Class I
Insulator	PTFE	ASTM D-1710	---	---	---
Contact	Beryllium Copper	ASTM B-196 UNS No. C17300 Temper TD04(H)	Gold Plate Nickel underplate	50µIN - 100µIN [1.27µM - 2.54µM]	Gold per ASTM B-488, Code C, Type II, Class 1.27
				50µIN - 100µIN [1.27µM - 2.54µM]	Nickel per SAE-AMS-QQ-N-290, Class I

**Electrical Specification:**  
IMPEDANCE, 50.0 Ohms NOMINAL.  
FREQUENCY, 65.0 GHz.

**Mechanical:**  
Operating temperature range: -55° C to +165° C.

- Interface definition, SMP3 male is designed and manufactured IAW MIL-STD-348 and will mate with SMP3 female connector designed and manufactured IAW MIL-STD-348.
- Mounting Patterns, Customer specific factors including transmission line topology, substrate thickness and material, board-stackup, operating frequency, etc. must be submitted to HUBER+SUHNER Astrolab for analysis prior to release of final performance levels and mounting configuration.

Type: 81 SMP3-S50-0-FD2		All dimensions after treatment in millimeter (mm)		
Assembly drawing	Released date:	alternative ID 29174S1-2-001	3D-ID PRO-01149826 A	Sheet: 1/1
description		ID	Release	
HUBER+SUHNER SMP3 Male Surface Mount		DOU-01171244	A	